

IGBT4 Modules

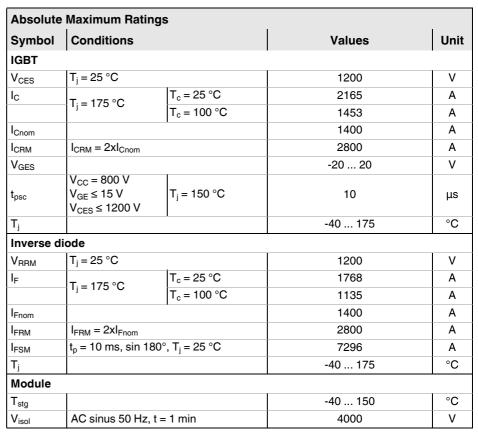
SKM1400GB12P4

Features

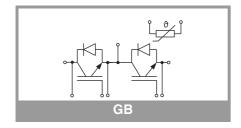
- · Symmetrical current sharing
- · Low-inductive module design
- High mechanical robustness
- UL recognized, file no. E63532

Typical Applications*

- Motor Drives
- · UPS Systems
- · Solar Inverters



Characteristics										
Symbol	Conditions		min.	typ.	max.	Unit				
IGBT										
V _{CE(sat)}	I _C = 1400 A	T _j = 25 °C		1.75	2.06	V				
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.18	2.44	V				
V _{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V				
		T _j = 150 °C		0.70	0.80	V				
r _{CE}	V _{GE} = 15 V chiplevel	T _j = 25 °C		0.68	0.83	mΩ				
		T _j = 150 °C		1.06	1.17	mΩ				
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_{C}=49.2$	mA	5	5.8	6.5	V				
I _{CES}	V _{GE} = 0 V, V _{CE} = 1200 V, T _j = 25 °C				6	mA				
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		81.6		nF				
C _{oes}		f = 1 MHz		5.28		nF				
C _{res}		f = 1 MHz		4.50		nF				
Q_{G}	V _{GE} = - 8 V+ 15 V			7500		nC				
R _{Gint}	T _j = 25 °C			8.0		Ω				
t _{d(on)}	$\begin{array}{c} V_{CC} = 600 \ V \\ I_{C} = 1400 \ A \\ V_{GE} = +15/\text{-}15 \ V \\ R_{G \ on} = 1 \ \Omega \\ R_{G \ off} = 1 \ \Omega \\ di/dt_{on} = 11 \ kA/\mu s \\ di/dt_{off} = 6.9 \ kA/\mu s \\ du/dt = 3300 \ V/\mu s \\ L_{s} = 36 \ nH \end{array}$	T _j = 150 °C		353		ns				
t _r		T _j = 150 °C		119		ns				
E _{on}		T _j = 150 °C		150		mJ				
t _{d(off)}		T _j = 150 °C		803		ns				
t _f		T _j = 150 °C		171		ns				
E _{off}		T _j = 150 °C		277		mJ				
R _{th(j-c)}	per IGBT			0.02	K/W					
R _{th(c-s)}	per IGBT (λ _{grease} =0.81 W/(m*K))			0.008		K/W				





SEMITRANS® 10

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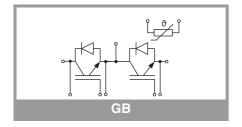
Features

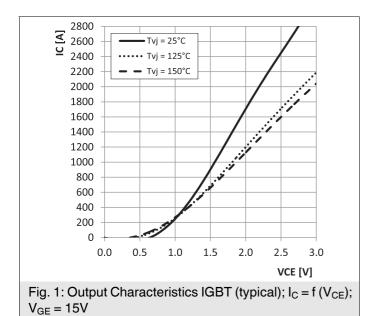
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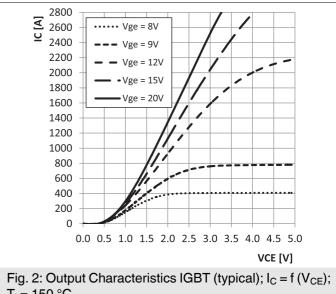
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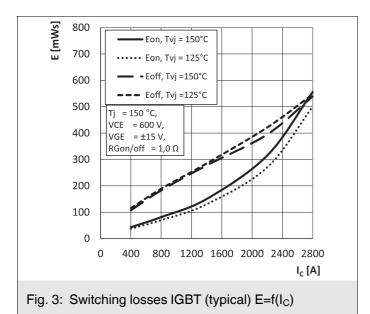
Characteristics										
Symbol	Conditions	min.	typ.	max.	Unit					
Inverse diode										
$V_F = V_{EC}$	I _F = 1400 A V _{GE} = 0 V chiplevel	T _j = 25 °C		2.06	2.37	V				
		T _j = 150 °C		2.04	2.35	V				
V _{F0}	chiplevel	T _j = 25 °C		1.30	1.50	V				
		T _j = 150 °C		0.90	1.10	V				
r _F	chiplevel	T _j = 25 °C		0.54	0.62	mΩ				
		T _j = 150 °C		0.81	0.89	mΩ				
I _{RRM}	$I_F = 1400 \text{ A}$ $di/dt_{off} = 11 \text{ kA/}\mu\text{s}$ $V_{GE} = \pm 15 \text{ V}$	T _j = 150 °C		1014		Α				
Q_{rr}		T _j = 150 °C		214		μC				
E _{rr}	$V_{CC} = 600 \text{ V}$	T _j = 150 °C		85		mJ				
R _{th(j-c)}	per diode			0.033	K/W					
R _{th(c-s)}	per diode (λ _{grease} =0.81 W/(m*K))			0.01		K/W				
Module										
L _{CE}				10		nΗ				
R _{CC'+EE'}	T _C = 25 °C			0.2		mΩ				
Rth _{(c-s)1}	calculated without thermal coupling (λ _{grease} =0.81 W/(m*K))			0.0022		K/W				
Rth _{(c-s)2}	including thermal coupling, Ts underneath module (λ _{grease} =0.81 W/(m*K))			0.0035		K/W				
Ms	to heat sink M5		4		6	Nm				
Mt		to terminals M8	8		10	Nm				
		to terminals M4	1.8		2.1	Nm				
W					1250	g				
Temperat	ure Sensor									
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω				
B _{100/125}	$R_{(T)} = R_{100} exp[B_{100/125}(1/T-1/T_{100})]; T[K];$			3550 ±2%		K				

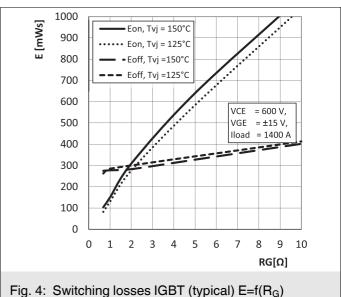


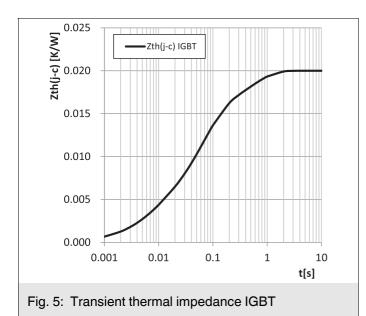












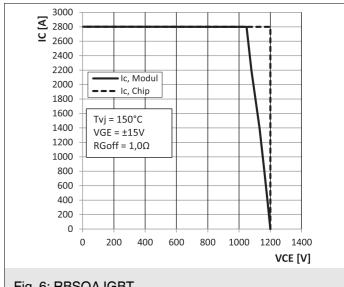
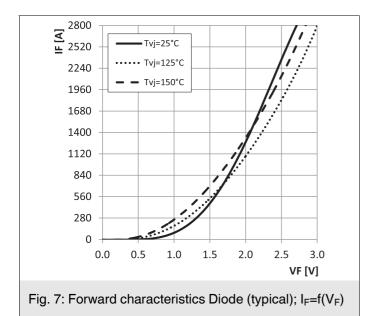
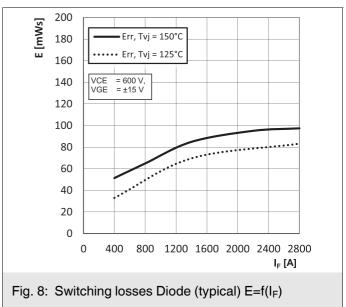
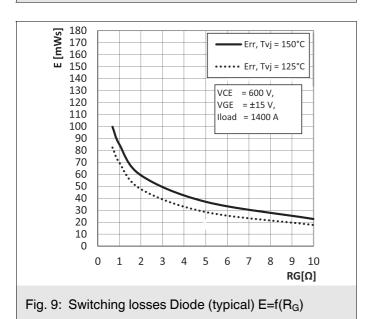
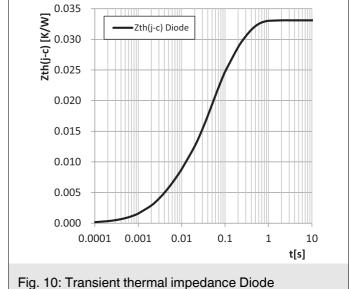


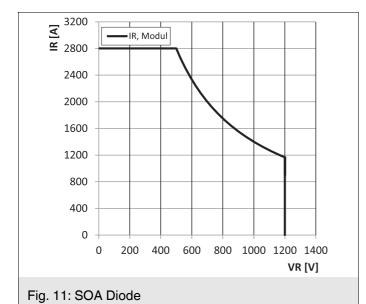
Fig. 6: RBSOA IGBT

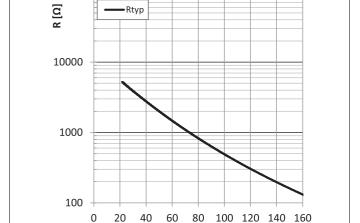








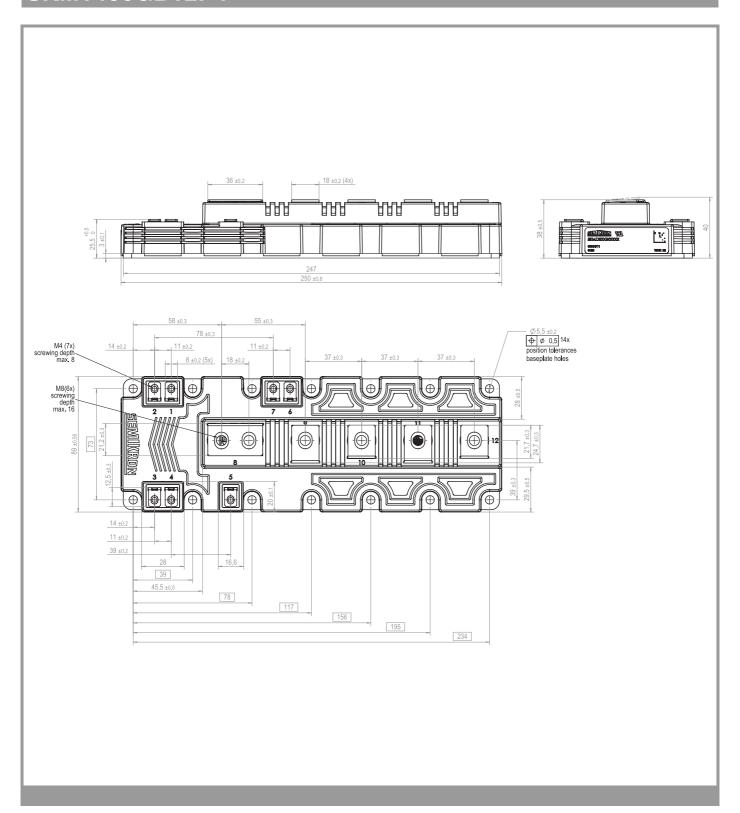


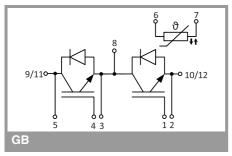


T[°C]

Fig. 12: NTC characteristics (typical)

100000





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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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